

ABSTRACT

A PROCESS CARRIER FOR FLEXIBLE SUBSTRATES

A substrate carrier which is used through beginning assembly operations such as solder reflow for attaching ball grid array devices to flexible substrates. The carrier includes a main structural support for centerly placing the substrate. The support member include two pairs of pins protruding from the support member to engage with a matching pair of datum apertures disposed inboard of the side edges of the substrate. A plurality of high temperature magnetic inserts are affixed into holes of the support member disposed parallel and outboard of the pins. The cover has two rows of apertures for engagement with the pins of the support member is attracted by the magnetic inserts forcing the outer periphery of the cover against the top surface of the substrate

(FIGURE 2 IS SUGGESTED FOR PUBLICATION)